

ABSTRACT OF THE DISCLOSURE

A deposited film forming apparatus ~~is provided~~  
which has a power applying electrode disposed above a  
flat plate type base member grounded, in a vacuum  
5 chamber, and a power source for supplying a power to  
the power applying electrode, the deposited film  
forming apparatus being constructed to supply the power  
from the power source to the power applying electrode  
so as to generate a plasma in a discharge space between  
10 the power applying electrode and a substrate disposed  
in opposition to the power applying electrode in the  
vacuum chamber and serving as an electrode in a pair  
with the power applying electrode, thereby decomposing  
a source gas introduced into the vacuum chamber to form  
15 a deposited film on the substrate, wherein the power  
applying electrode is fixed to the base member with the  
power applying electrode being isolated from the base  
member. ~~A deposited film forming method using the  
apparatus is also provided. This permits the power  
20 applying electrode to be fixed to the base member while  
isolating the power applying electrode from the base  
member, thereby preventing deformation of the power  
applying electrode. As a consequence, occurrence of  
plasma intrusion or abnormal discharge is prevented  
25 between the power applying electrode and the base  
member.~~